

AB356N6T

Photocoupler

FEATURES

- · High collector-emitter Voltage
- Opaque type, mini-flat package
- . Subminiature type (The volume is smaller than that of our conventional DIP type by as far as 30%)
- Isolation voltage between input and output Viso: 3750Vrms
- · Employs double transfer mold technology
- Package: 1000 pcs / reel · Moisture sensitivity level: 4
- · RoHS compliant

APPLICATIONS

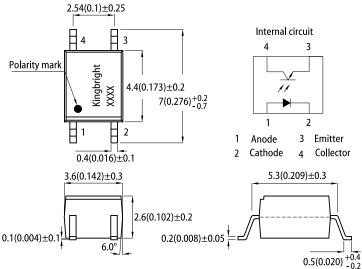
- · Hybrid substrates that require high density mounting
- Programmable controllers

NOTES ON HANDLING

Cautions regarding electrical noise

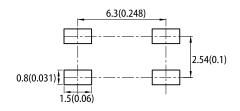
Please ensure the power supply is stable at all times. Even if the designed operating voltage is within specification limits, sudden voltage spikes at startup may damage the component.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: ± 0.15)



- Notes:

 1. All dimensions are in millimeters (inches).

 2. Tolerance is ±0.5(0.02") unless otherwise noted.

 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

ELECTRICAL / OPTICAL CHARACTERISTICS at T₄=25°C

	Parameter		Symbol	Value			Unita	Took Conditions
				Min.	Тур.	Max.	Units	Test Conditions
	Forward voltage		V _F	-	1.2	1.4	V	I _F =20mA
Input	Peak forward voltage		V_{FM}	-	-	3.0	V	I _{FM} =0.5A
	Reverse current		I _R	-	-	10	μA	V _R =4V
Output	Collector dark current		I _{CEO}	-	-	10 ⁻⁷	Α	I _F =0mA,V _{CE} =20V
	Collector-emitter breakdown voltage		BV _{CEO}	80	-	-	V	I _F =0mA,I _C =0.1mA
	Emitter-collector breakdown voltage		BV _{ECO}	6	-	-	V	I _F =0mA,I _E =10μA
Transfer characteristics	Current transfer ratio		CTR	130	-	400	%	I _F =5mA,V _{CE} =5V
	Collector-emitter saturation voltage		V _{CE(sat)}	-	0.1	0.2	V	I _F =20mA,I _C =1mA
	Response time	Rise time	t _r	-	6	-	μs	V_{CE} =2V, I_{C} =2mA R_{L} =100 Ω
		Fall time	t _f	-	8	-	μs	

1. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

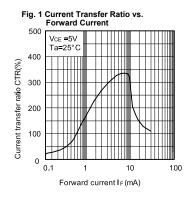


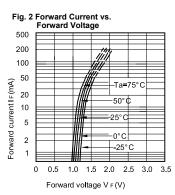
ABSOLUTE MAXIMUM RATINGS at T_A=25°C

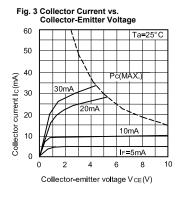
	Parameter	Symbol	Rating	Unit
Input	Forward current	l _F	50	mA
	Reverse voltage	V _R	6	V
	Power dissipation	P _D	70	mW
Output	Collector-emitter voltage	$V_{\sf CEO}$	80	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	Ic	50	mA
	Collector power dissipation	P _C	150	mW
Total power dissipation		P _{tot}	170	mW
Isolation voltage [1]		$V_{\rm iso}$	3750	Vrms
Operating temperature		T_{opr}	-30~+100	°C
Storage temperature		T _{stg}	-40~+125	°C

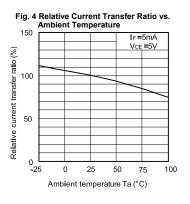
Notes:

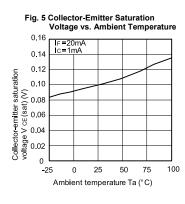
TECHNICAL DATA

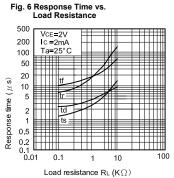


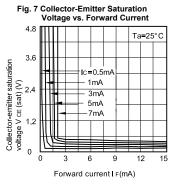


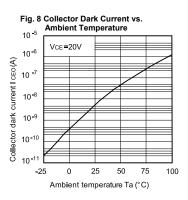










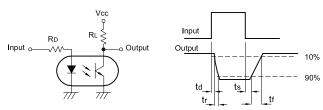


^{1.40} to 60% RH,AC for 1 minute. 2.Relative humidity levels maintains

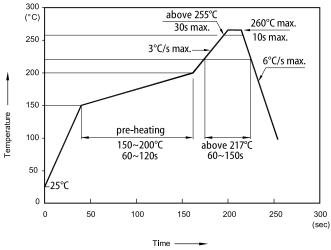
ve humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Test Circuit for Response Time



REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



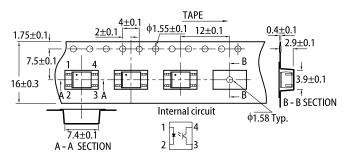
- Notes:

 1. Don't cause stress to the LEDs while it is exposed to high temperature.

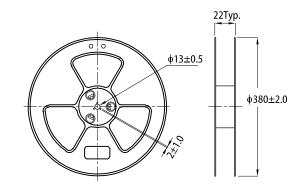
 2. The maximum number of reflow soldering passes is 2 times.

 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

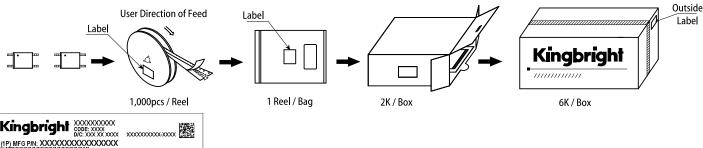
TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units: mm)



PACKING & LABEL SPECIFICATIONS





RESTRICTIONS ON PRODUCT USE

- The information in this document represents typical usage and is provided for technical reference.
- The information in this document is subject to change without notice. Please refer to the latest version of this document for the most updated information.

 Please ensure this product is used in accordance with the electrical and environmental specifications and tolerances listed in this document. If the usage exceeds the specification range, Kingbright will not be responsible for any subsequent issues.
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